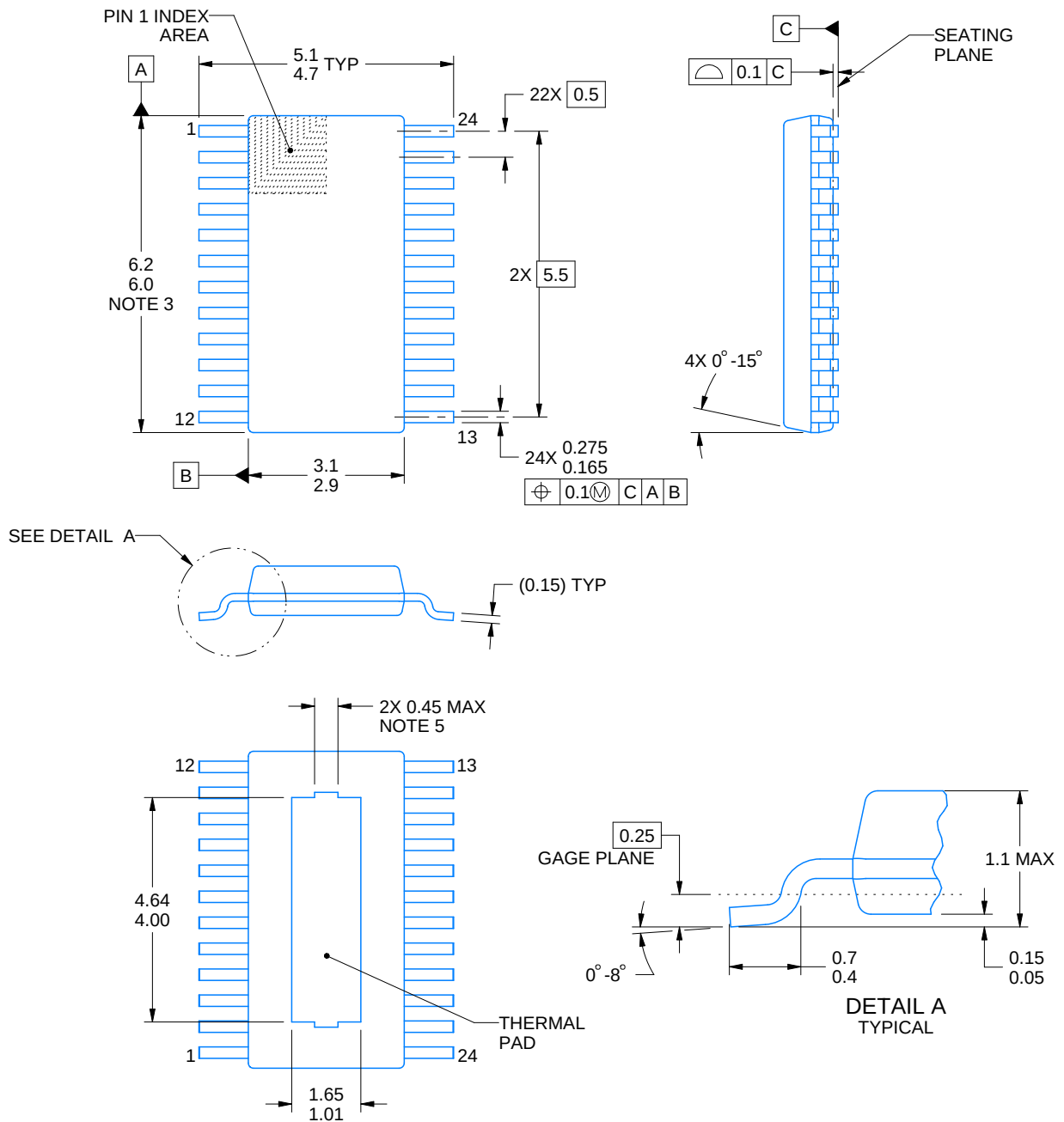




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NOTES:

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

DGQ0024A

PowerPAD™ VSSOP - 1.1 mm max height

24X (1.45)
24X (0.3)
1
(R0.05) TYP
22X (0.5)
SYMM
CL
(Ø 0.2) TYP VIA
SOLDER MASK DEFINED PAD
12
(2.2) NOTE 9
(1.65)
SYMM
CL
METAL COVERED BY SOLDER MASK
SEE DETAILS
24
(4.64) (6.1) NOTE 9
(1.6) TYP
13
(0.65) TYP
(4.4)

The image contains two diagrams illustrating PCB manufacturing options for a rectangular feature.

Left Diagram: NON-SOLDER MASK DEFINED (PREFERRED)

- SOLDER MASK OPENING:** Points to the white rectangular area.
- METAL:** Points to the blue rectangular area surrounding the opening.
- EXPOSED METAL:** Points to a small black dot within the white area.
- 0.05 MAX ALL AROUND:** Dimension line indicating the maximum width of the metal area.
- NON-SOLDER MASK DEFINED (PREFERRED):** Label for this manufacturing option.

Right Diagram: SOLDER MASK DEFINED

- METAL UNDER SOLDER MASK:** Points to the blue rectangular area.
- SOLDER MASK OPENING:** Points to the white rectangular area.
- EXPOSED METAL:** Points to a small black dot within the white area.
- 0.05 MIN ALL AROUND:** Dimension line indicating the minimum width of the metal area.
- SOLDER MASK DEFINED:** Label for this manufacturing option.

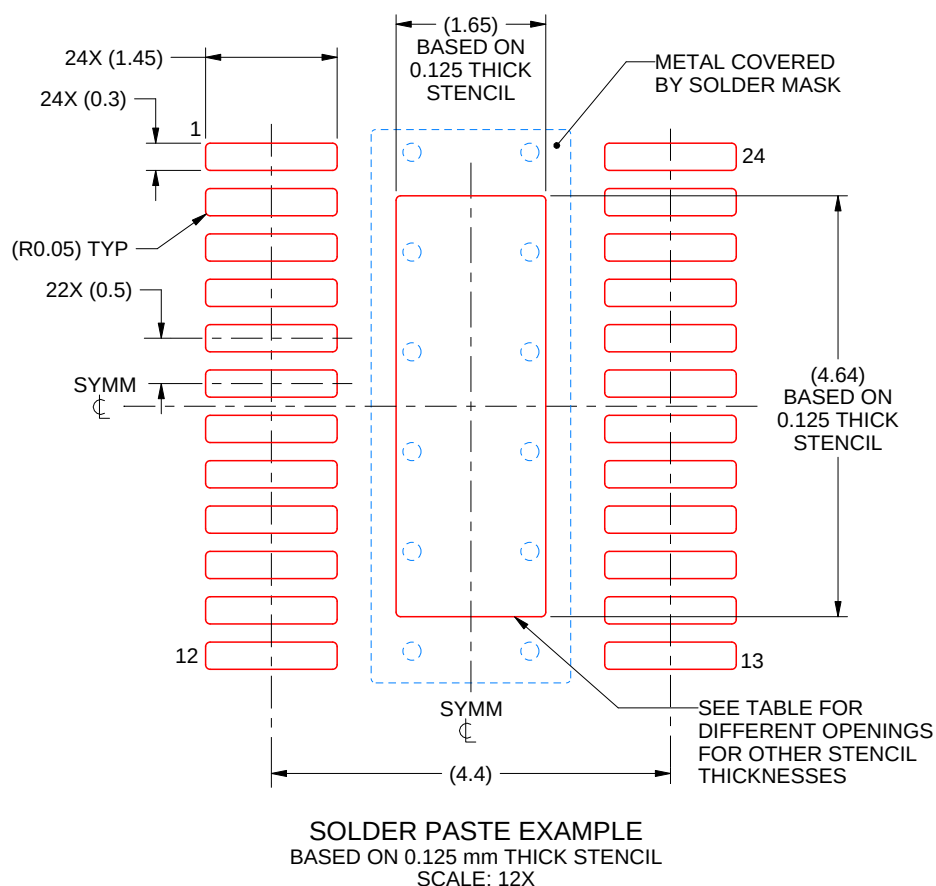
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6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

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PowerPAD™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	1.84 X 5.19
0.125	1.65 X 4.64 (SHOWN)
0.15	1.51 X 4.24
0.175	1.39 X 3.92

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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